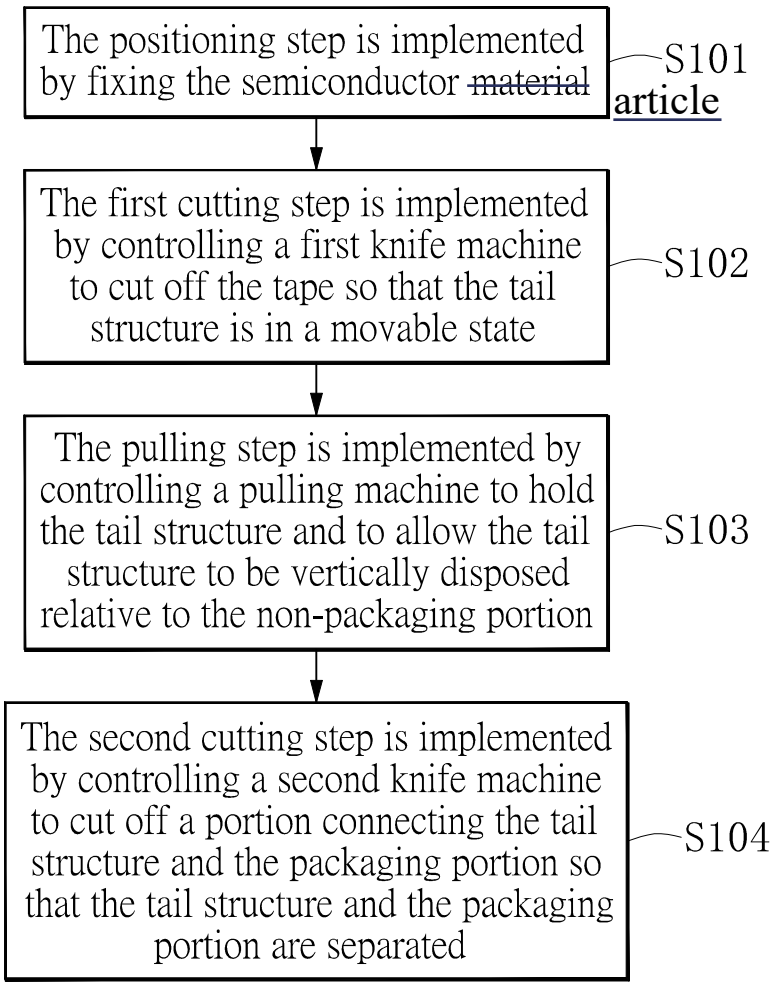

The positioning step is implemented by fixing the semiconductor ~~material~~ article
S101
The first cutting step is implemented by controlling a first knife machine to cut off the tape so that the tail structure is in a movable state
S102
The pulling step is implemented by controlling a pulling machine to hold the tail structure and to allow the tail structure to be vertically disposed relative to the non-packaging portion
S103
The second cutting step is implemented by controlling a second knife machine to cut off a portion connecting the tail structure and the packaging portion so that the tail structure and the packaging portion are separated
S104

FIG. 25

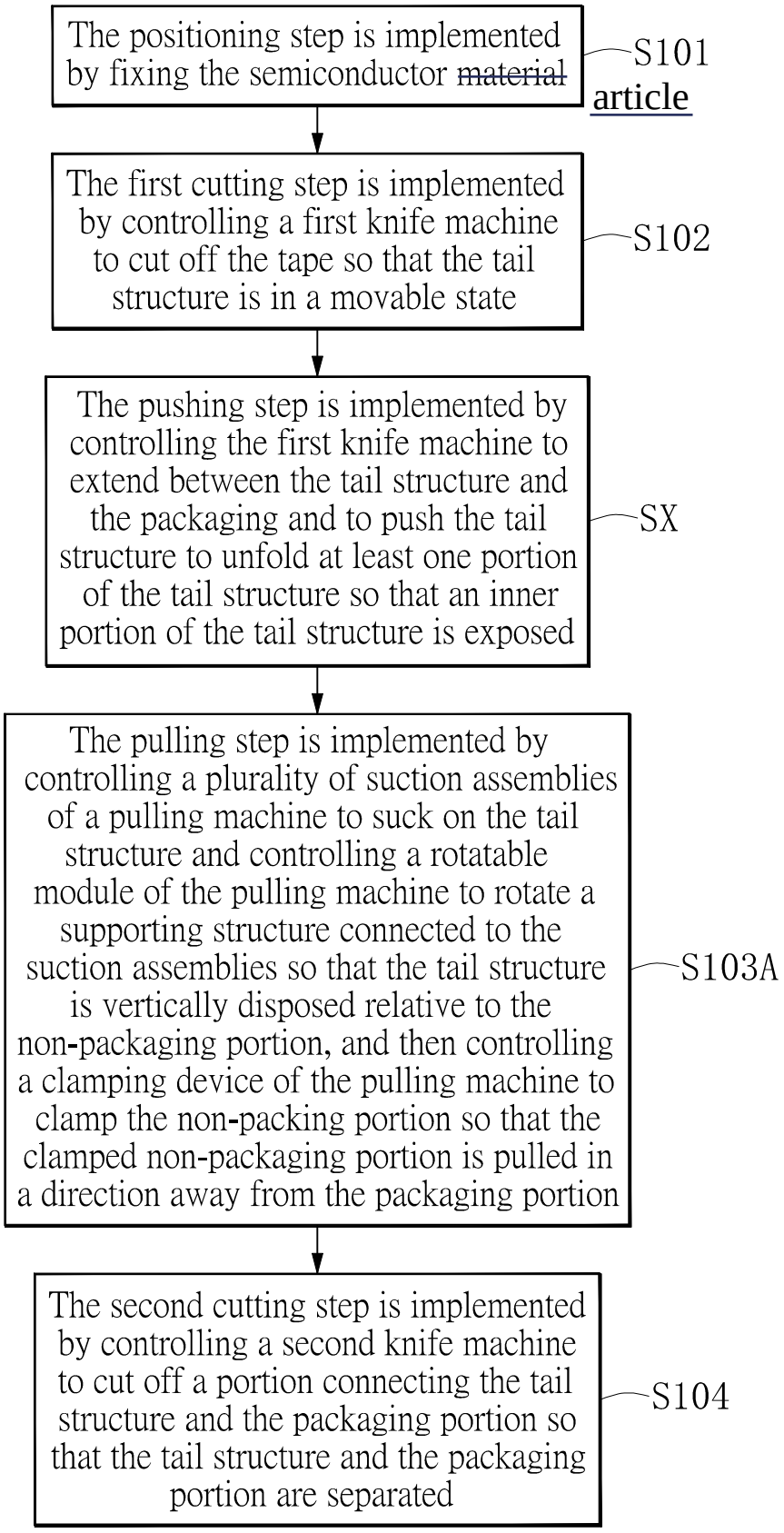

The positioning step is implemented by fixing the semiconductor ~~material~~ article
S101
The first cutting step is implemented by controlling a first knife machine to cut off the tape so that the tail structure is in a movable state
S102
The pushing step is implemented by controlling the first knife machine to extend between the tail structure and the packaging and to push the tail structure to unfold at least one portion of the tail structure so that an inner portion of the tail structure is exposed
SX
The pulling step is implemented by controlling a plurality of suction assemblies of a pulling machine to suck on the tail structure and controlling a rotatable module of the pulling machine to rotate a supporting structure connected to the suction assemblies so that the tail structure is vertically disposed relative to the non-packaging portion, and then controlling a clamping device of the pulling machine to clamp the non-packing portion so that the clamped non-packaging portion is pulled in a direction away from the packaging portion
S103A
The second cutting step is implemented by controlling a second knife machine to cut off a portion connecting the tail structure and the packaging portion so that the tail structure and the packaging portion are separated
S104

FIG. 26